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North America System in Package (SiP) Technology Market (2016-2022)

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Abstracts

The concept of System in Package (SiP) gained prominence as the demand for miniaturization and higher functionality grew within the semiconductor packaging industries. With ICs and the major electrical components being packaged into a single module, the overall performance, reliability, and efficiency of the module increased substantially.

The North America System in Package (SiP) Technology Market is would register a growth of 11.7% CAGR during the forecast period. SiP Technology prominently used in the applications such as consumer electronics, telecommunication, and automotive. Growing demand for portable electronic devices and adoption of SiP in graphic cards and processors are some the prominent factors that are responsible for the market growth. Additionally, the demand for high frequency electronic gadgets would further add to the market opportunities. 2.5-D IC Packaging is the leading segment within the global SiP market, and it is expected to maintain the trend throughout the forecast period. However, 3-D IC Packaging segment would be the fastest growing market during the forecast period.

The report highlights the adoption of System in Package (SiP) Technology in North America. Based on the Type, the Global System in Package (SiP) Technology market is segmented into 2-D IC Packaging, 2.5-D IC Packaging and 3-D IC Packaging segments. Based on the Packaging Type, the market is bifurcated into Flat Packages, Pin Grid Arrays, Surface Mount, Small Outline Packages and Other Packaging segments. The North America System in Package (SiP) Technology market is further segmented into Wire Bond, Flip Chip segments based on the Interconnection Technology. Further, the market is segmented into Consumer Electronics, Automotive, Telecommunication, Industrial System, Aerospace & Defense and Other segments

based on the various applications. The countries included in the report are U.S, Canada, Mexico and Rest of North America.

Key Players profiled in the report includes Amkor Technology Inc., Jiangsu Changjiang Electronics Technology Co. Ltd., Chipmos Technologies Inc., Powertech Technology Inc., Ase Group, Renesas Electronics Corporation, Samsung Electronics Co. Ltd. and Toshiba Corporation.

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